NOTES, UNLESS OTHERWISE SPECIFIED:

1. The netname "V3P3V" represents connection to the +3.3V power buss
2. The netname "V1P8V" represents connection to the +1.8V power buss
3. The netname "V1P8V_SW" represents connection to the +1.8V switched power buss
4. The netname "SYS_PWR" represents connection to the +4.5V power buss.
5. The netname "VBIAS" represents connection to the +18.0V DMD power buss.
6. The netname "VOFS" represents connection to the +10.0V DMD power buss.
7. The netname "VRST" represents connection to the -14.0V DMD power buss.
8. The netname "GND" represents connection to the ground plane.
9. A "Z" suffix on a signal name indicates an active low signal.
10. All components with designators "U*", "Q*", and "D*" are electrostatic discharge sensitive.
11. All resistor values are in ohms.
12. All capacitor values in microfarads unless otherwise specified.

COMPUTER GENERATED DRAWING - DO NOT REVISE MANUALLY

REVISIONS

REV	DESCRIPTION	DATE	APPROVED
-	Draft Release	07/24/2014	HPC
A	ECO 2143348: REV A Release		

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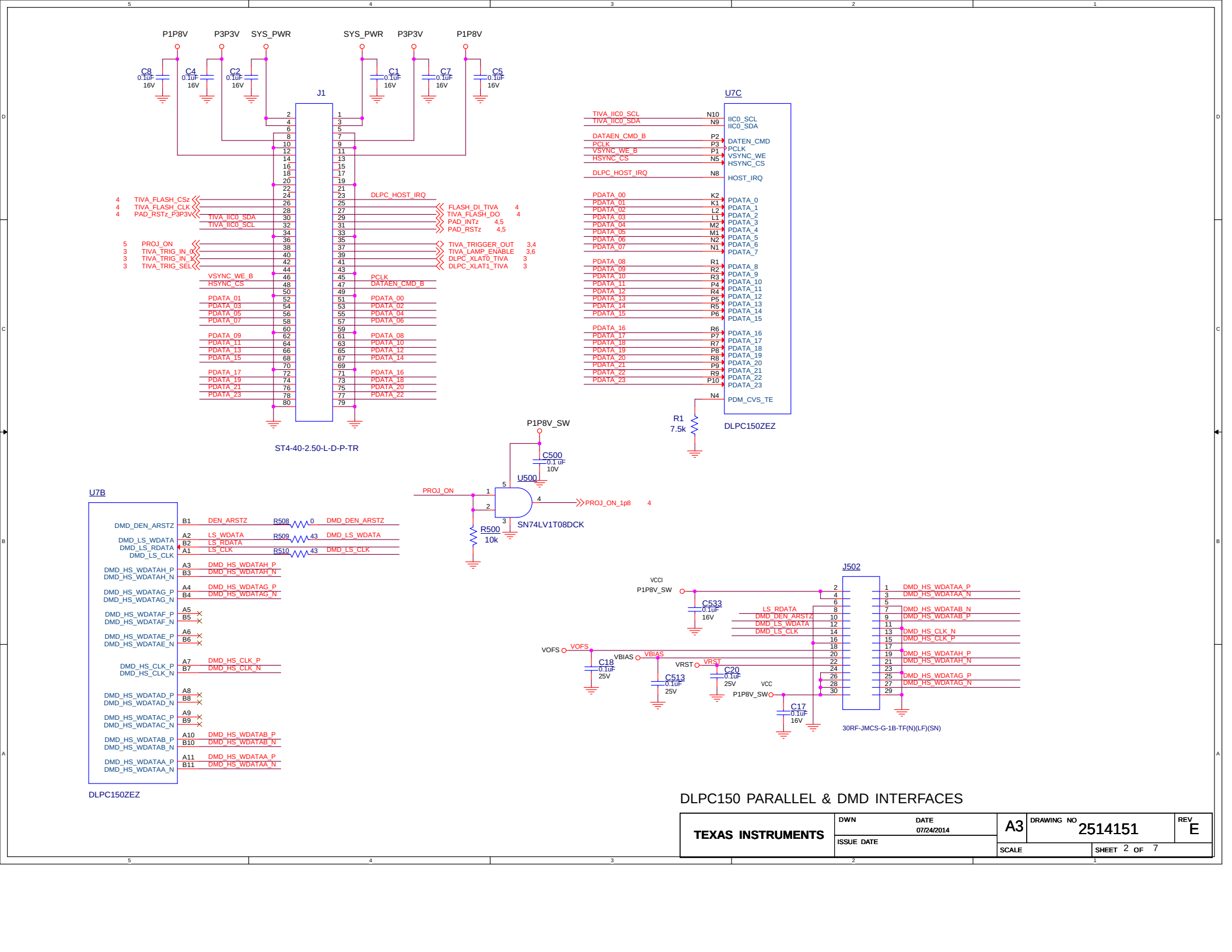
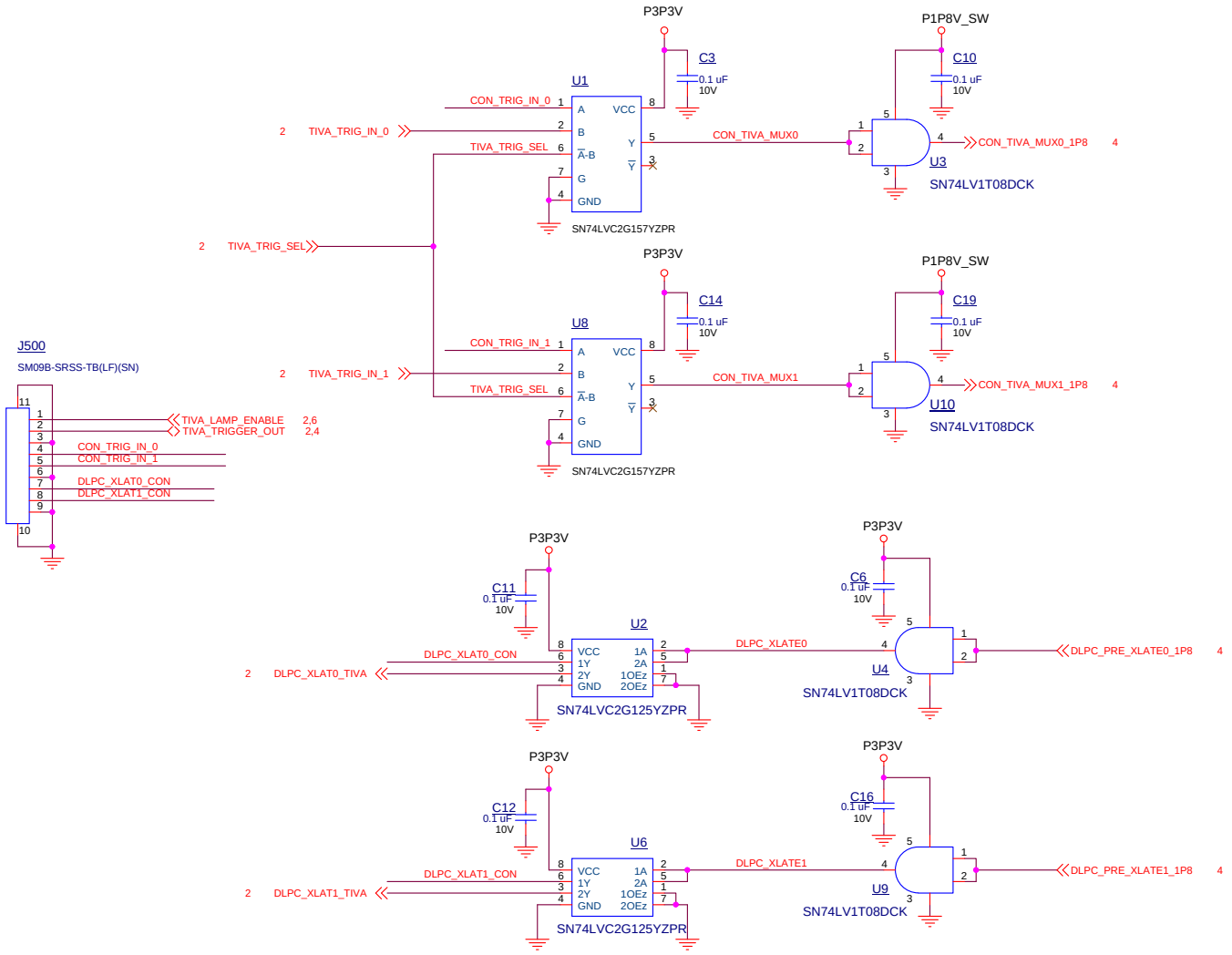
		ENGR	
		APVD	TITLE: ESD, NIRscan Nano DLPC 150 Board
		MFG	
	0314CP	QA	
NEXT ASSY	USED ON		A3 / DRAWING NO 2514151 / REV E
APPLICATION		SW Allegro Design Entry 16.6	SCALE / SHEET 1 of 7



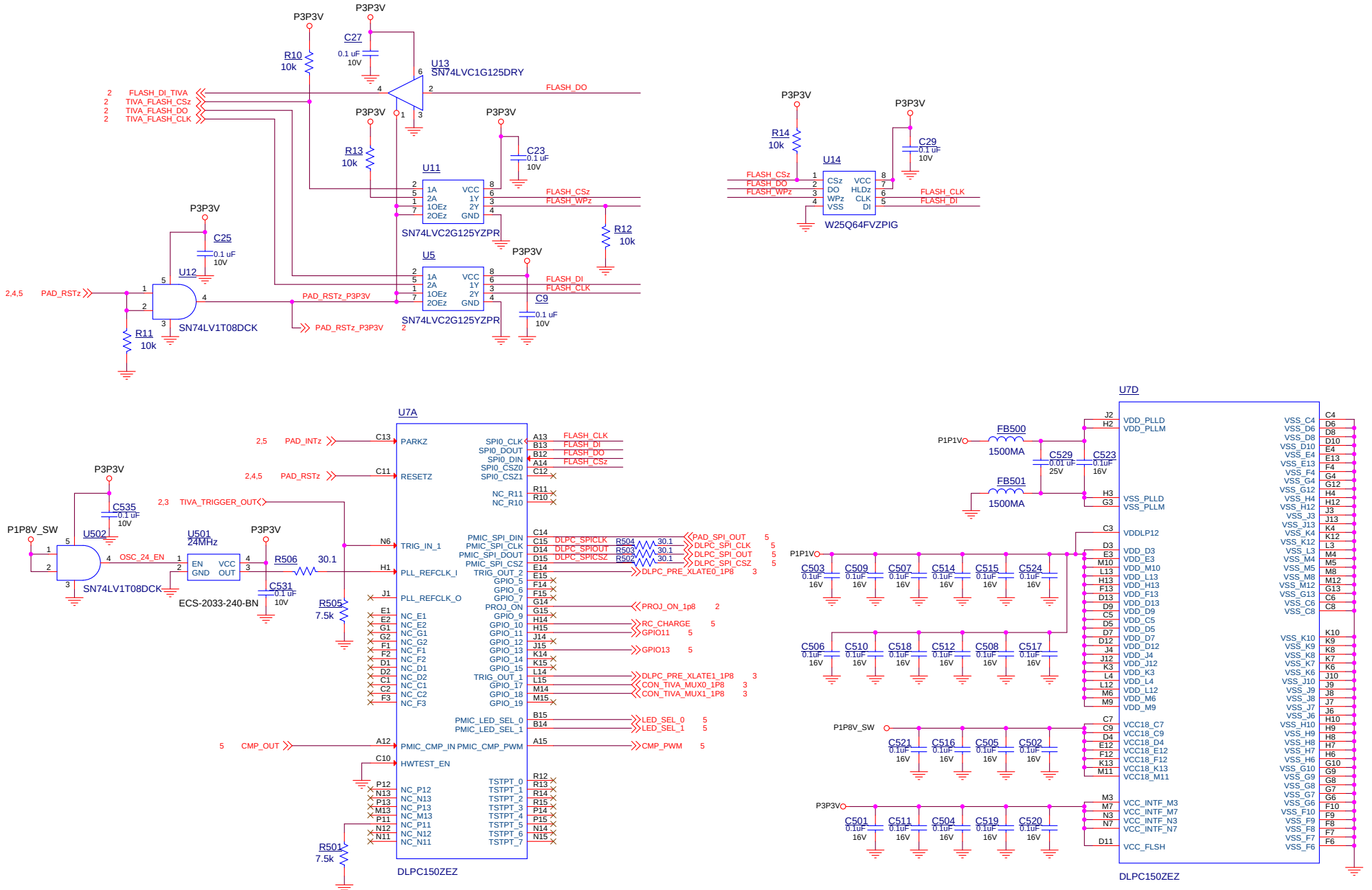
DLPC150 PARALLEL & DMD INTERFACES

TEXAS INSTRUMENTS	DWN	DATE 07/24/2014	A3	DRAWING NO 2514151	REV E
	ISSUE DATE		SCALE	SHEET 2 OF 7	



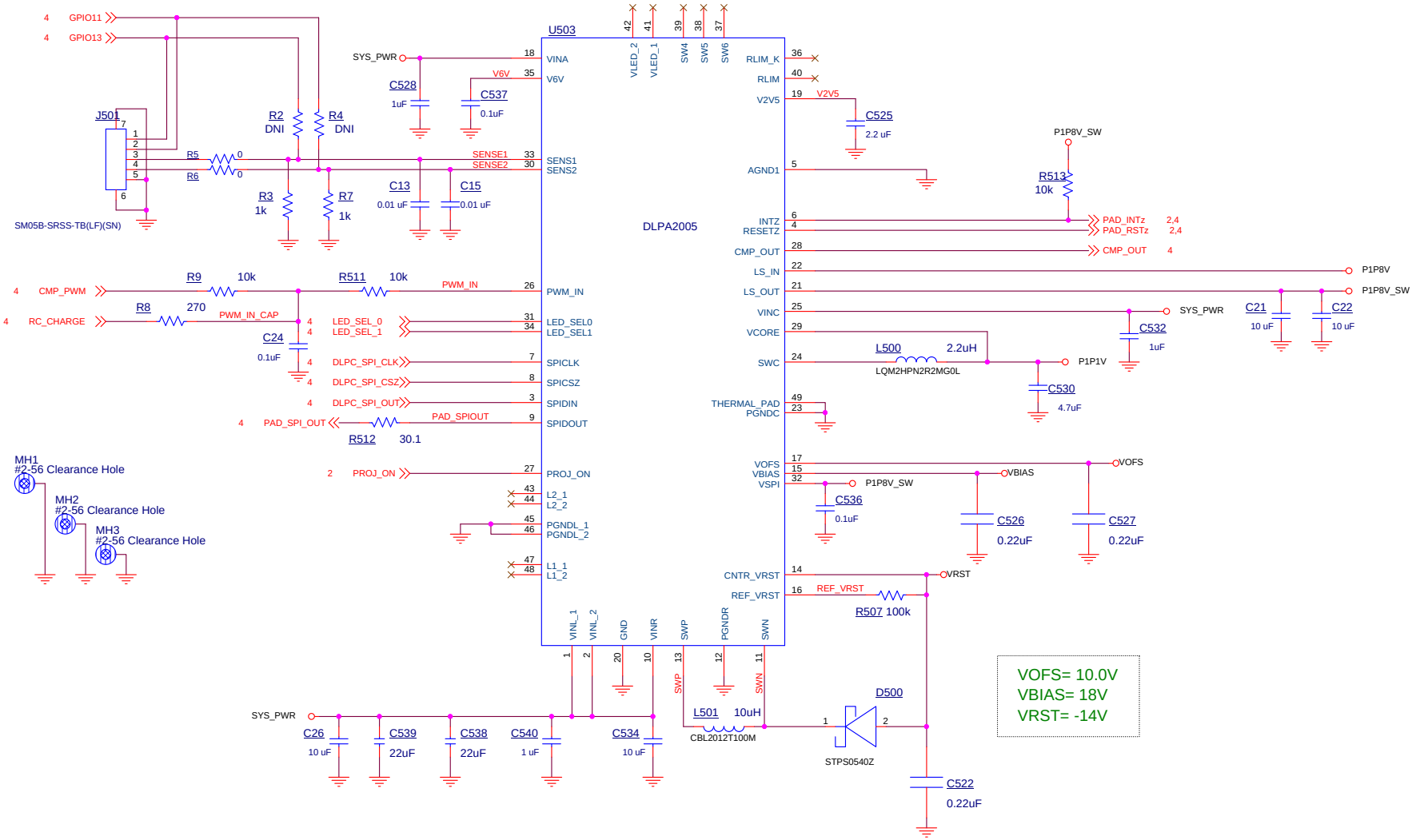
TIVA - DPP - CONNECTOR - I/O

TEXAS INSTRUMENTS	DWN	DATE 07/24/2014	A3	DRAWING NO 2514151 REV E
	ISSUE DATE		SCALE	SHEET 3 OF 7



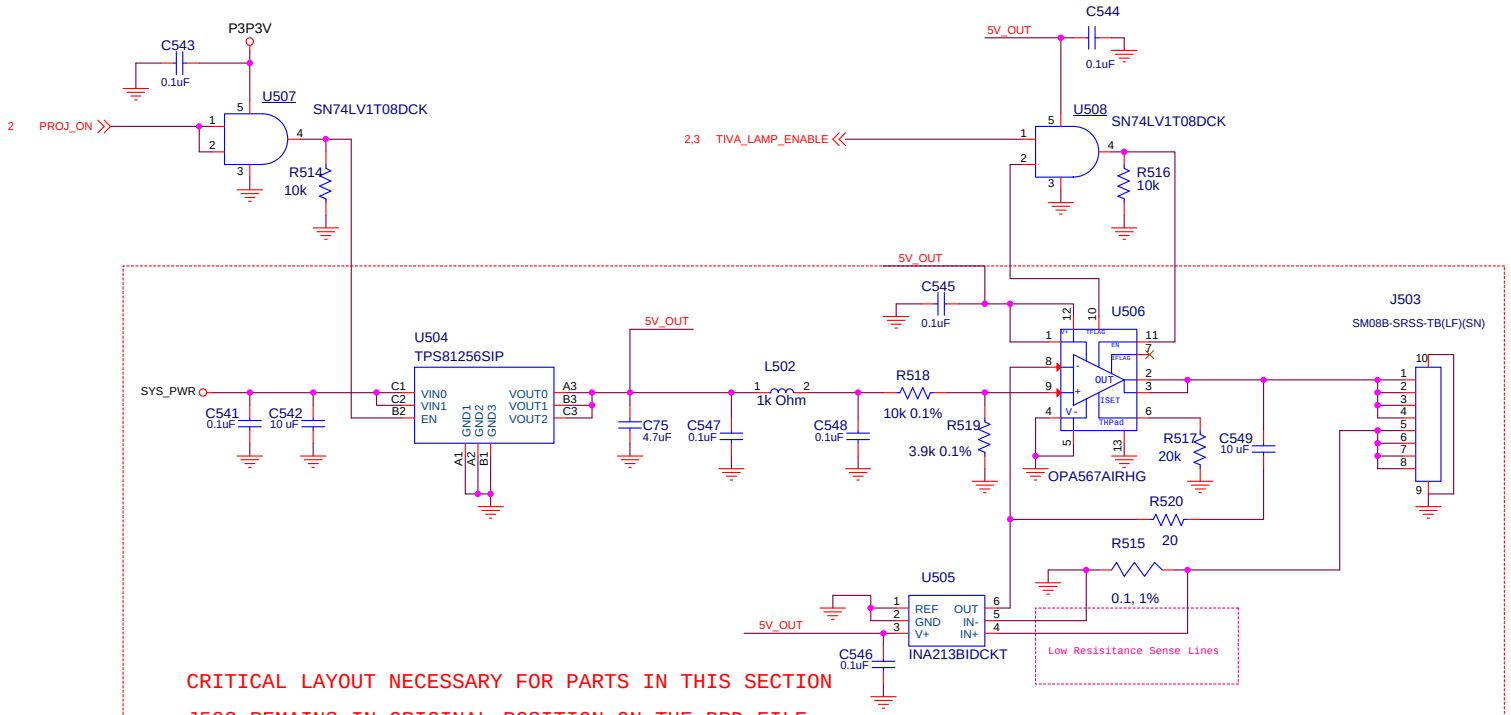
DLPC150 MISC & POWER

TEXAS INSTRUMENTS	DWN	DATE 07/24/2014	A3	DRAWING NO 2514151 REV E
	ISSUE DATE		SCALE	SHEET 4 OF 7



PAD 2005

TEXAS INSTRUMENTS	DWN	DATE 07/24/2014	A3	DRAWING NO 2514151	REV E
	ISSUE DATE		SCALE	SHEET 5 OF 7	



LAMP DRIVER

TEXAS INSTRUMENTS	DWN	DATE 07/24/2014	A3	DRAWING NO 2514151 REV E
	ISSUE DATE		SCALE	SHEET 6 OF 7

Revision History

Rev. -- : Draft Release ~ 07/24/2014

Rev. A: ECO 2143348: ~ 07/??/2014

Rev. A: Added three 2-56 mounting holes: 08/22/2014 MR.

Rev. A: Changed U7 from DLPC150ZEZ to DLPC3435ZEZ: 08/29/2014 MR.

Rev. A: Changed U503 from DLPC2005 to DLPA2005: 08/29/2014 MR.

Rev. B: Changed J502 pinout:switched odd/even pins to match DMD board pinout: 10/17/2014 MR.(page2)

Rev. B: Changed U13 : P3P3V connection to pin6, 10/17/2014 MR.(page4)

Rev. B: Changed U14 : Changed part to MX25L3206EZUI12G requires new PCB footprint. MR.(page5)

Rev. B: Changed U503 : Changed symbol SPICLK to pin7 and SPIDIN to pin3. 10/17/2014 MR.(page5)

Rev. B: Changed C26, C540 to 0603 : C538,C539, C541, C542 to 0805 Changed 10/21/2014 MR.(page5)

Rev. C: Adderd U7A pinN6 connection to net TIVA_EXP_I2C_SDA 2/7/2015 MR.(page4)

Rev. C: Removed L502, C541,C28, C542, C30, R516, R518, R517, R515 and J503 traces from PAD2005 2/7/2015 MR.(page5).

Rev. C: Added Lamp Driver circuit to schematic 2/7/2015 MR.(page7).

Rev. D: Added C549 and R520 to Lamp Driver circuit U506 output compensation. 3/12/2015 MR.(page7).

Rev. E: Changed U7 pin names to match DLPC150 datasheet pin names. 11/11/2015 MR.

Rev. E: Changed signal names to TIVA LAMP_ENABLE and TIVA_TRIGGER_OUT pg2,3,4,6. 11/11/2015 MR.

Schematic Revision History

TEXAS INSTRUMENTS	DWN	DATE 07/24/2014	A3	DRAWING NO 2514151 REV E
	ISSUE DATE		SCALE	SHEET 7 OF 7